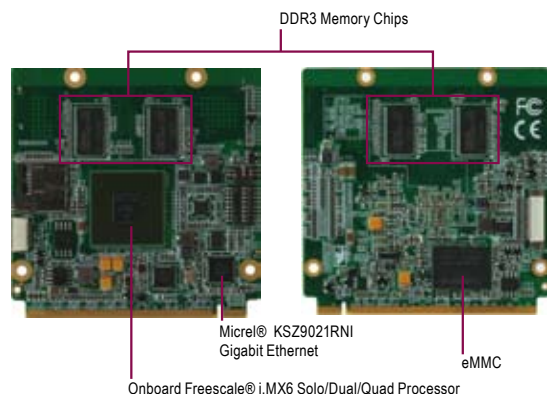


AQ7-IMX6

Qseven CPU Module with Onboard Freescale® i.MX6 Solo/Dual/Quad ARM Cortex A9 Processor



Features

- Freescale® i.MX6 Solo/Dual/Quad Processor
- Onboard DDR3 800 Memory 1GB (Solo/Dual)
- Onboard DDR3 1066 Memory 2GB (Quad)
- Gigabit Ethernet x 1
- 24-bit Dual-Channel LVDS LCDs (Optional)
- I2S Audio Interface
- SATA x 1, eMMC (Optional)
- USB2.0 x 5, PCI-Express [x1] x 1
- Qseven Module Size, 70mm x 70mm , Qseven Rev. 2.0



Specifications

System	
Form Factor	Qseven, Qseven Rev. 2.0
Processor	Freescale® i.MX6 Solo 1.0GHz Processor Freescale® i.MX6 Dual 1.0GHz Processor Freescale® i.MX6 Quad 1.0/1.2GHz Processor
System Memory	Onboard DDR3/1GB, Max. 1 GB (Solo/Dual) Onboard DDR3/1GB, Max. 2 GB (Quad)
Chipset	—
I/O Chipset	—
Ethernet	Micrel® KSZ9021RNI for 10/1000/1000Base
BIOS	—
Wake On LAN	Yes
Watchdog Timer	Integrated Watch Dog and Timer
H/W Status Monitoring	Integrate advanced power management
Expansion Interface	PCI Express [x1] x1 CAN Bus x1 SMBUS x1 UART x1 SDIO x1
Power Requirement	+5V DC
Power Consumption (Typical)	—
Board Size	2.75" x 2.75" (70mm x 70mm)
Gross Weight	0.44 lb (0.2 Kg)
Operation Temperature	32 °F ~ 140 °F (0 °C ~ 60 °C) or -40 °F ~ 185 °F (-40 °C ~ 85 °C) for WITAS 2
Storage Temperature	-40 °F ~ 185 °F (-40 °C ~ 85 °C)
Operation Humidity	0% ~ 90% relative humidity, non-condensing
MTBF (Hours)	—
Display	
	Supports LCD/CRT/HDMI
Resolution	Up to 1400 x 1050 (SXGA) @ 60Hz for CRT Up to 1366 x 768 or 1280 x 800 (WXGA) @ 60Hz for LCD
LCD Interface	Up to 24-bit dual channel LVDS (optional)
I/O	
Storage	1 SATA (3GB/s), eMMCx1(optional)
Serial Port	1 (Tx/Rx)
Parallel Port	—
USB	USB 2.0 x 5(Shared with 1 x USB OTG client)
PS/2 Port	—
I2C	1
Audio	I2S
GPIO	8-bit

Packing List

- Product CD
- AQ7-IMX6

Ordering Information

- TBD

Optional Accessories

- TBD

ECB-970

Qseven Rev. 2.0 Carrier Board for ARM/X86 Solutions

Launching in Q2

Features

- Supports Qseven Module
- Support ARM/x86 Based
- Supports Gigabit Ethernet, RJ-45
- Up to 24-bit Dual Channel LVDS Connector or EDP, DP or HDMI
- High Definition Audio or I2S Audio Interface
- SATA Port x 2, SDIO x 1
- USB 2.0 x 8, USB 3.0 x 2, USB OTG
- LPC Connector x 1
- Qseven 2.0
- 9.65" Form Factor



Specifications

System	
Form Factor	MTX
I/O Chipset	Winbond W83627DHG-P or Fintek F81866 (optional)
Ethernet	10/1000/1000Base-TX, RJ-45 x 1 (From CPU module)
Expansion Interface	PCI Express [x4] x 1, LPC Connector x 1 (For Super I/O Card only)
Power Requirement	+5V DC
Power Consumption (Typical)	—
Board Size	9.65" x 9.65" (243.84mm x 243.84mm)
Gross Weight	1.32 lb (0.6 Kg)
Operation Temperature	32°F ~ 140°F (0°C ~ 60°C)
Storage Temperature	-40°F ~ 185°F (-40°C ~ 85°C)
Operation Humidity	0% ~ 90% relative humidity, non-condensing
MTBF (Hours)	—
Display	LVDS or EDP, DP or HDMI
LCD Interface	Up to 24-bit dual channel LVDS
I/O	—
Storage	SATA x 2, SDIO x 1
Serial Port	RS-232 x 1, RS-232/422/485 x 1
Parallel Port	—
USB	USB 2.0 x 8, USB3.0 x 2, USB OTG
PS/2 Port	—
I2C	1
Audio	Audio Jack, supports Line-in, Line-out, Microphone, Headphone (ARM base only)
Debug LED	—

Packing List

- Product CD
- ECB-970